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Product Change Notification - KMIO-24FXKZ027

Date: 24 Aug 2016

Product Category: Touch Sensing Technologies; Analog (Thermal, Power Management & Safety); Analog (Linear &

Mixed Signal) AND Interface

Notification subject: CCB 2719 Initial Notice: Qualification of G700Y mold compound for selected products available on

10L VDFN package at ANAP assembly site.

Notification text: PCN Status:

Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of G700Y mold compound for selected products available on 10L VDFN package at

ANAP assembly site.

Pre Change:

Assembled at ANAP assembly site using GE7470LA mold compound.

Post Change:

Assembled at ANAP assembly site using G700Y mold compound.

Pre and Post Change Summary:

	Pre Change	Post Change			
Assembly Site	ANAP	ANAP			
Wire material	Au wire	Au wire			
Die attach material	AMK06	AMK06			
Molding compound material	GE7470LA	G700Y			
Lead frame material	C194	C194			

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To Improve On-Time Delivery Performance by qualifying G700Y mold compound at ANAP assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

February 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date.

Time Table Summary:

	August 2016				^	February 2017			
Workweek	31	32	33	34		5	6	7	8
Initial PCN Issue Date				Х					
Qual Report Availability						Х			
Final PCN Issue Date						Х			

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

August 24, 2016: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): PCN_KMIO-24FXKZ027_Qual Plan.pdf

PCN_KMIO-24FXKZ027_Affected CPN.pdf PCN_KMIO-24FXKZ027_Affected CPN.xlsx

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Affected Catalog Part Numbers (CPN)

PCN KMIO-24FXKZ027
CATALOG_PART_NBR
CAP1006-1-AIA-TR
CAP1106-1-AIA-TR
CAP1133-1-AIA-TR
CAP1206-1-AIA
CAP1206-1-AIA-TR
CAP1206-2-AIA-TR
CAP1296-1-AIA
CAP1296-1-AIA-TR
CAP1296-2-AIA-TR
EMC1183-A-AIA-TR
EMC1184-A-AIA-TR
EMC1187-1-AIA-TR
EMC1188-1-AIA-TR
EMC1403-1-AIA-TR
EMC1403-2-AIA-TR
EMC1413-A-AIA-TR
EMC1414-A-AIA-TR
EMC1444-A-AIA-TR
EMC1464-A-AIA-TR
PAC1710-1-AIA-TR
PAC1720-1-AIA-TR
PAC1921-1-AIA-TR